

10/038,291

L Number	Hits	Search Text	DB	Time stamp
1	760	capillary and wire and bond\$ and coin\$ and @ad<20010104	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 17:07
2	252	(capillary and wire and bond\$ and coin\$ and @ad<20010104) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:40
3	162	((capillary and wire and bond\$ and coin\$ and @ad<20010104) and semiconductor) and coat\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:41
4	29	((capillary and wire and bond\$ and coin\$ and @ad<20010104) and semiconductor) and (coat\$ near4 wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:41
5	92	capillary and wire and bond\$ and (coin coined coining) and @ad<20010104	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 17:08
6	41	(capillary and wire and bond\$ and (coin coined coining) and @ad<20010104) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 17:24
7	516	(wave adj solder\$4) and @ad<20010104 and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 17:25
8	65	((wave adj solder\$4) and @ad<20010104 and semiconductor) and core	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 17:25
9	56	((((wave adj solder\$4) and @ad<20010104 and semiconductor) and core) and bond\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 17:25
-	79	ibm.as. and (flip adj chip) and @ad<20010104	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:38
-	798	(flip adj chip) and @ad<20010104 and solder and core	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 11:35
-	286	((flip adj chip) and @ad<20010104 and solder and core) and (dip\$4 wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 13:47

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-	917	(solder near4 wave) and @ad<20010104 and (semiconductor ic chip (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 13:48
-	112	((solder near4 wave) and @ad<20010104 and (semiconductor ic chip (integrated adj circuit))) and core	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 14:11
-	701	(solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and core and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 14:14
-	179	(solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and (solder near4 core) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 14:14
-	137	((solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and (solder near4 core) and (bump ball)) and (semiconductor IC (integrated adj circuit) chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 14:15